

Title (en)

JOINING DEVICE FOR FIXING COMPONENTS ON A CARRIER SURFACE BY MEANS OF GLUING

Title (de)

FÜGEVORRICHTUNG ZUM BEFESTIGEN VON KLEINTEILIGEN BAUELEMENTEN AN EINER TRÄGERFLÄCHE DURCH KLEBEN

Title (fr)

DISPOSITIF D'ASSEMBLAGE POUR FIXER PAR COLLAGE DES ELEMENTS DE PETITE TAILLE SUR UN SUPPORT

Publication

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Application

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Abstract (en)

[origin: WO2005095045A1] The invention relates to a joining device for fixing a small component, particularly a bolt (28) provided with an adhesive flange (29), to a carrier surface (30) with the aid of a heat-activatable adhesive that causes an adhesive bond between the component and the carrier surface. The joining device has an induction coil (3) for heating the component and/or adhesive and a holding device (4) by means of which the component is held when the joining device is moved to gluing position. A support surface (30) is provided for the component in the opposite side of the carrier surface. The component can be moved to said support surface from the outside. The holding device (4) is moved by the induction coil (3) to the component and has an electromagnet for generating a retaining force directed against the support surface.

IPC 8 full level

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See references of WO 2005095045A1

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